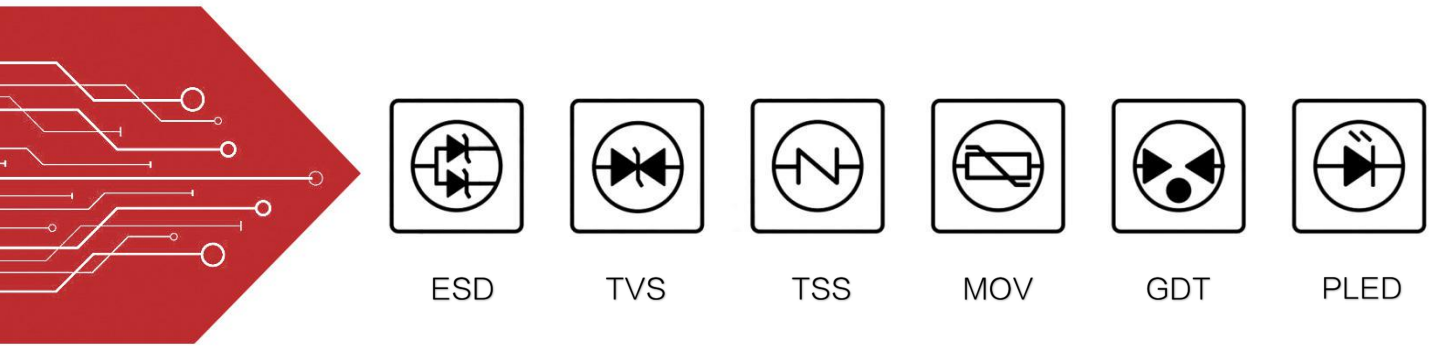
MSKSEMI
SEMICONDUCTOR



Product data sheet

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FEATURES

- Low forward voltage
- High current capability
- High forward surge capability
- Low power losses，High efficiency
- Guarding for over voltage protection

APPLICATIONS

Low VF Schottky barrier rectifier are designed for high freqency, miniature switched mode power supplies such as adapters ,lighting and on-board DC/DC conerters

Primary Characteristic	
I_O	2*5A
V_{RRM}	100V
I_{FSM}	120A
V_F	0.65V
$T_J$max	150℃
Assembly code	AI

MECHANICAL DATA

- **Case:** Molded plastic
- **Polarity:** As marked
- **Mounting Position:** Any
- **Molded Plastic:** UL Flammability Classification Rating 94V-0
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Solder bath temperature 275℃ maximum,10s per JESD22-B106

Maximum Ratings (Per Leg) at Ta=25°C unless otherwise specified				
Characteristics		Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	100	V
Working Peak Reverse Voltage		V_{RWM}	100	V
Maximum DC Blocking Voltage		V_{DC}	100	V
Maximum Average Forward Rectified Current	Per Leg	I_O	5	A
	Total		10	
Peak Forward Surge Current,8.3 ms Single Half Sine-wave		I_{FSM}	120	A
Operating Temperature Range		T_J	150	°C
Storage Temperature Range		T_{STG}	-40 to +150	°C
Typical Thermal Resistance (Note1) TO-220AB,TO-263,TO-252 TO-220F		$R_{\theta JC}$	 2 4	°C/W

Note1: Thermal resistance from Junction to case per leg mounted on heatsink.

Electrical Characteristics (Per Leg) unless otherwise specified					
Characteristics		Symbol	Value		Unit
Forward Voltage Drop(Note2)		V_F	Typ.	Max.	V
at I_F=2A	TA=25°C		0.68	-	
	TA=125°C		0.56	-	
at I_F=3A	TA=25°C		0.72	-	
	TA=125°C		0.60	-	
at I_F=5A	TA=25°C		0.76	0.85	
	TA=125°C		0.65	-	
Maximum Reverse Current at V_R=100V	TA=25°C	I_R	0.001	0.1	mA
	TA=125°C		0.6	-	mA

Note2:Pulse test: 300 μs pulse width, 1 % duty cycle

RATINGS AND CHARACTERISTIC CURVES

FIG.1 MAXIMUM FORWARD CURRENT DERATING CURVE

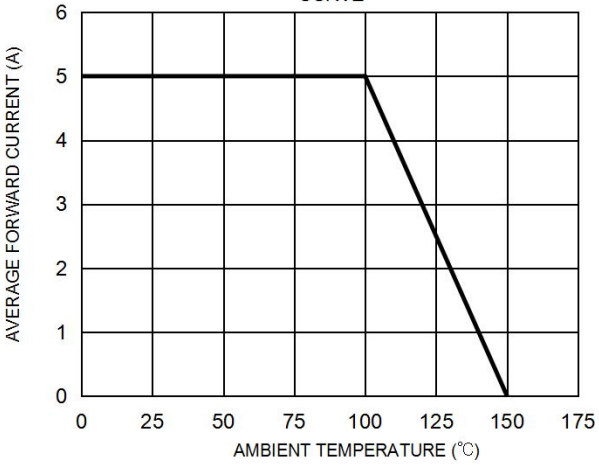


FIG. 2 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT PER LEG

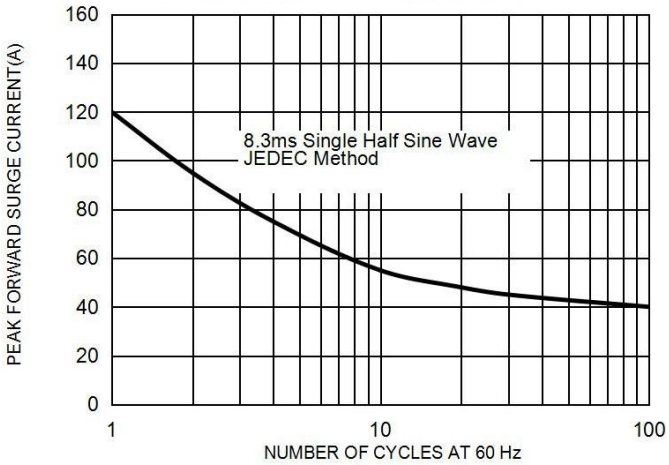


FIG. 3 TYPICAL FORWARD CHARACTERISTICS PER LEG

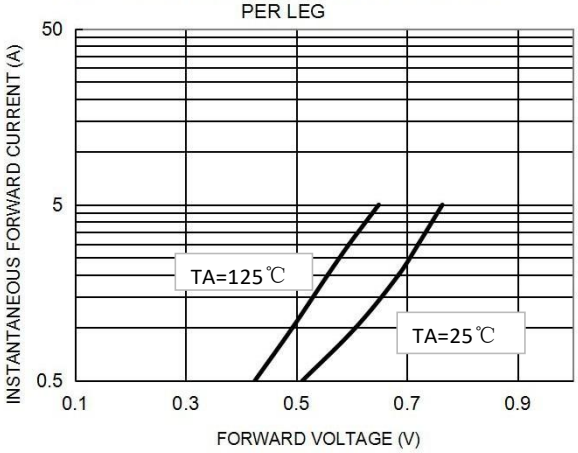
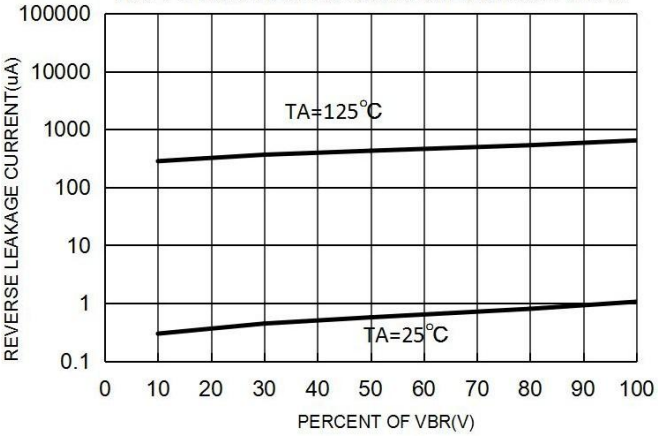
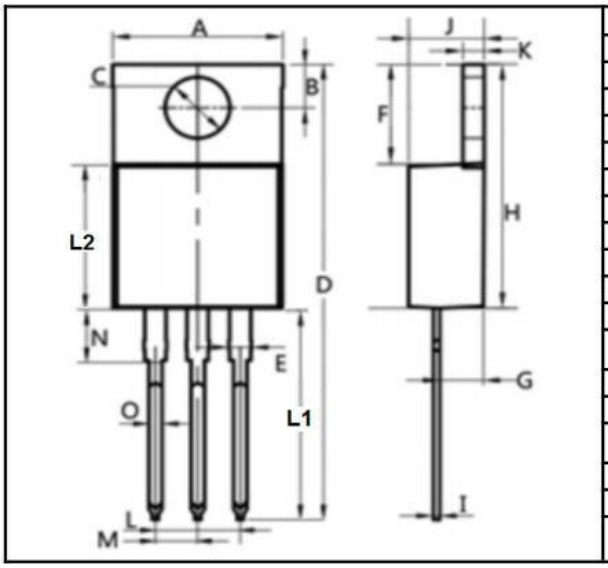


FIG. 4 TYPICAL REVERSE CHARACTERISTICS PER LEG



Package Outline Dimensions millimeters

TO-220AB



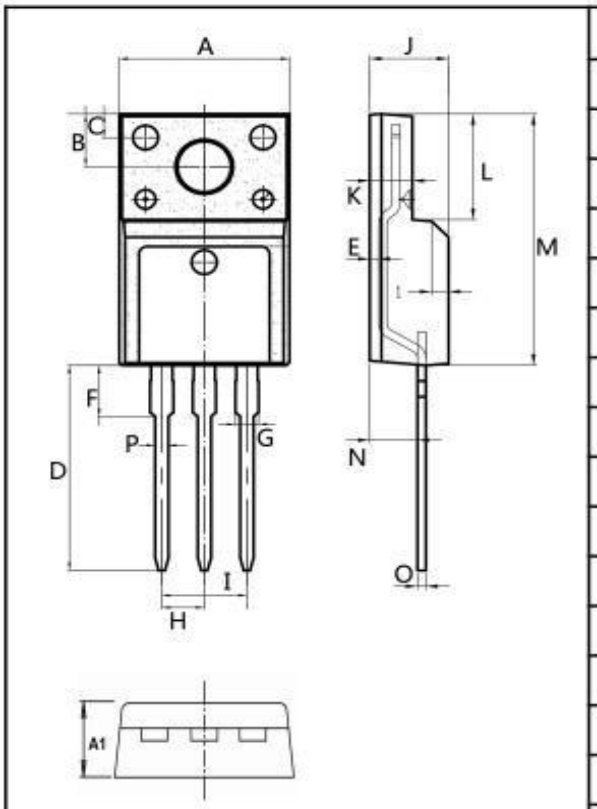
Dim.	Min.	Max.
A	10.15	10.35
B	2.50	2.95
C	3.70	3.90
D	28.5	29.5
E	1.20	1.40
F	6.20	6.55
G	2.4	2.6
H	15.0	16.0
I	0.35	0.42
J	4.3	4.55
K	1.25	1.35
L	Typ5.08	
L1	13	14
L2	8.5	9.5
M	Typ2.54	
N	2.8	3.5
O	0.70	0.90
All Dimensions in millimeter		

REEL SPECIFICATION

P/N	PKG	QTY
MBR10100CT-MS	TO-220AB	50pcs/tube 1000pcs/box

Package Outline Dimensions millimeters

TO-220F



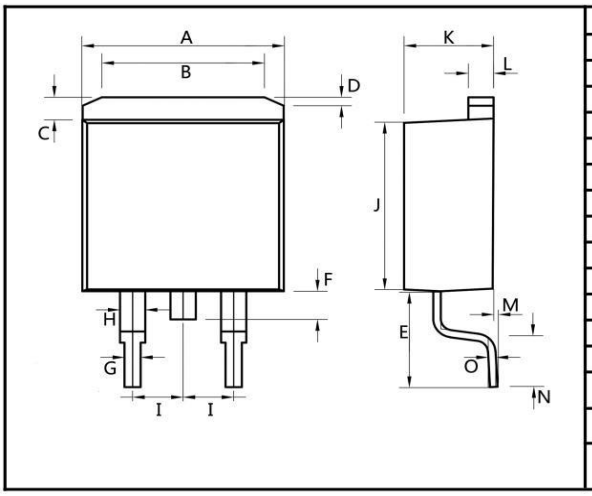
Dim.	Min.	Max.
A	9.95	10.25
A1	4.5	5.0
B	2.95	3.25
C	1.25	1.45
D	12.80	13.20
E	0.40	0.60
F	2.8	3.5
G	1.30	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.60	4.75
K	2.45	2. 65
L	6.5	6.8
M	15.4	16.0
N	2.75	3.05
O	0.45	0.55
P	0.70	0.90
All Dimensions in millimeter		

REEL SPECIFICATION

P/N	PKG	QTY
MBR10100FCT-MS	TO-220F	50pcs/tube 1000pcs/box

Package Outline Dimensions millimeters

TO-263



Dim.	Min.	Max.
A	10.15	10.35
B	6	8
C	1.2	1.5
D	0.55	1.0
E	4.3	5.3
F	1.4	1.6
G	0.75	0.85
H	1.2	1.5
I	Typ2.54	
J	8.5	9.5
K	4.3	4.55
L	1.25	1.35
M	0.02	0.23
N	2.2	2.8
O	0.30	0.40
All Dimensions in millimeter		

REEL SPECIFICATION

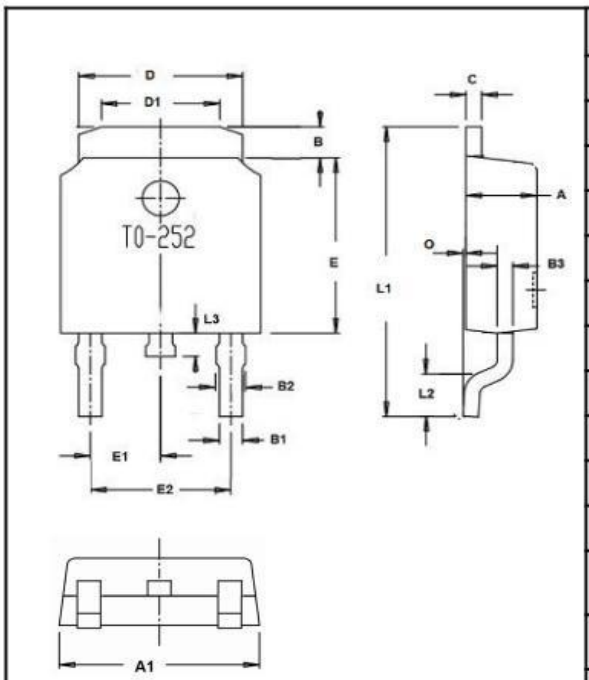
P/N	PKG	QTY
MBR10100DC-MS	TO-263	50pcs/tube 1000pcs/box

REEL SPECIFICATION

P/N	PKG	QTY
MBR10100DC-R-MS	TO-263	800pcs

Package Outline Dimensions millimeters

TO-252



Dim.	Min.	Max.
A	2.1	2.5
A1	6.3	6.9
B	0.96	1.42
B1	0.74	0.86
B2	0.74	0.94
C	Typ0.5	
D	5.33	5.53
D1	3.65	4.05
E	6.0	6.2
E1	Typ2.29	
E2	Typ4.58	
O	0	0.15
L1	9.9	10.5
L2	Typ1.65	
L3	0.6	1.0
All Dimensions in millimeter		

REEL SPECIFICATION

P/N	PKG	QTY
MBR10100CS-MS	TO-252	2500

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